Form PTO-1595 (Rev. 09/04) OMB No. 0651-0027 (exp. 6/30/2005)

Name:

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Y. Jae Kim - 53,128

Name of Person Signing

04-26-2005



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To the Director of the U.S. Patent and Trademark Office: Please	record the attached documents or the new address(es) below.			
Name of conveying party(ies)/Execution Date(s):	2. Name and address of receiving party(ies)			
Sang S. Kim (03/06/2005), Kyoung S. Kwon (03/06/2005), Jung C. Gong (03/06/2005), and Hyeon S. Hwang (03/06/2005)	Name: Samsung Electro-Mechanics Co., Ltd. Internal Address:			
Execution Date(s): in parentheses after inventor name	Street Address:			
Additional name(s) of conveying party(ies) attached? Yes X No				
3. Nature of Conveyance: x Assignment Merger	314, Maetan-3dong Youngtong-gu, Suwon-si			
当 * 				
Security Agreement Change of Name	City: Kyunggi-do			
Government Interest Assignment	State:			
Executive Order 9424, Confirmatory License	Country: Republic of Korea Zip: 443-743			
Other	Additional name(s) & address(es) Yes X No attached:			
A. Patent Application No.(s) Additional numbers attached? Name and address to whom correspondence concerning document should be mailed: Name: Joseph R. Robinson DARBY & DARBY P.C. Internal Address: Atty. Dkt.: 20345/0202702-US0 Street Address: P.O. Box 5257	B. Patent No.(s) Yes X No 6. Total number of applications and patents involved: 7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00 Authorized to be charged by credit card Authorized to be charged to deposit account X Enclosed None required (government interest not affecting title)			
City: New York State: NY Zip: 10150-5257	8. Payment Information a. Credit Card Last 4 Numbers			
State: NY Zip: 10150-5257 Phone Number: (212) 527-7783	Expiration Date			
Fax Number: (212) 753-6237	b. Deposit Account Number			
Email Address: jrobinson@darbylaw.com	Authorized User Name			
. Signature:	April 15, 2005 ——————————————————————————————————			
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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

PHOTODIODE INTEGRATED CIRCUIT HAVING MULTIPLE GAIN STATES

application for United States Letters Patent on	, (Application No.); and
WILLDEAS Sameung Flactro Machanics Co.	I to a corporation of Korea whose nost of	effice address is

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an

WHEREAS, <u>Samsung Electro-Mechanics Co., Ltd</u>, a corporation of Korea, whose post office address is <u>314, Maetan-3dong</u>, <u>Youngtong-gu</u>, <u>Suwon-si</u>, <u>Kyunggi-do 443-743</u>, <u>Republic of Korea</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. , filed) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s):

Full Name of Sole or First Assignor Assignor's Signature		Date		
Sang Suk KIM	김상성	6.3.2005		
Address	Citizenship			
944-2003, Lotte APT., Yeongtong-dong, Paldal-gu, Suwon-si, Kyunggi-Do 442-				
724, Korea	KOREA			

WITNESS:

I certify that I know or have satisfactory evidence that Sang Suk KIM is the person who appeared before me, and that he acknowledged that he signed this instrument and acknowledged it to be his free and voluntary act for the uses and purposes mentioned in the instrument.

1

PATENT REEL: 016485 FRAME: 0704

ATTORNEY DOCKET NO: SOLE/JOINT INVENTION (U.S. Rights Only)

Dated: March 6. 2005	x Engles	
Printe	od Name: Signature Pae Hy-	e Ryun
*********	************	*******
Full Name of Sole or First Assignor	Assignor's Signature	Date
Kyoung Soo KWON	W	6.3.2005
Address		Citizenship
112-602, Hwanggolmaeul 1-danji Ap Suwon-si, Kyunggi-Do 443-739, Koro	KOREA	
	WITNESS:	
***********	Signature Bue Hy	******
Full Name of Sole or First Assignor Jung Chul GONG	Assignor's Signature	Date March 6, 2003
Address		Citizenship
A-101, Hosu heights, 57-12, Songpa 1	-dong, Songpa-gu, Seoul 138-849, Korea	KOREA
	WITNESS:	
before me, and that he acknowledged that act for the uses and purposes mentioned Dated: March b. Joo	satisfactory evidence that Jung Chul GO at he signed this instrument and acknowledge in the instrument. x Signature ed Name:	

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PATENT REEL: 016485 FRAME: 0705